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(12) **United States Design Patent** (10) **Patent No.:** **US D934,821 S**  
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(54) **SEMICONDUCTOR DEVICE**  
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See application file for complete search history.

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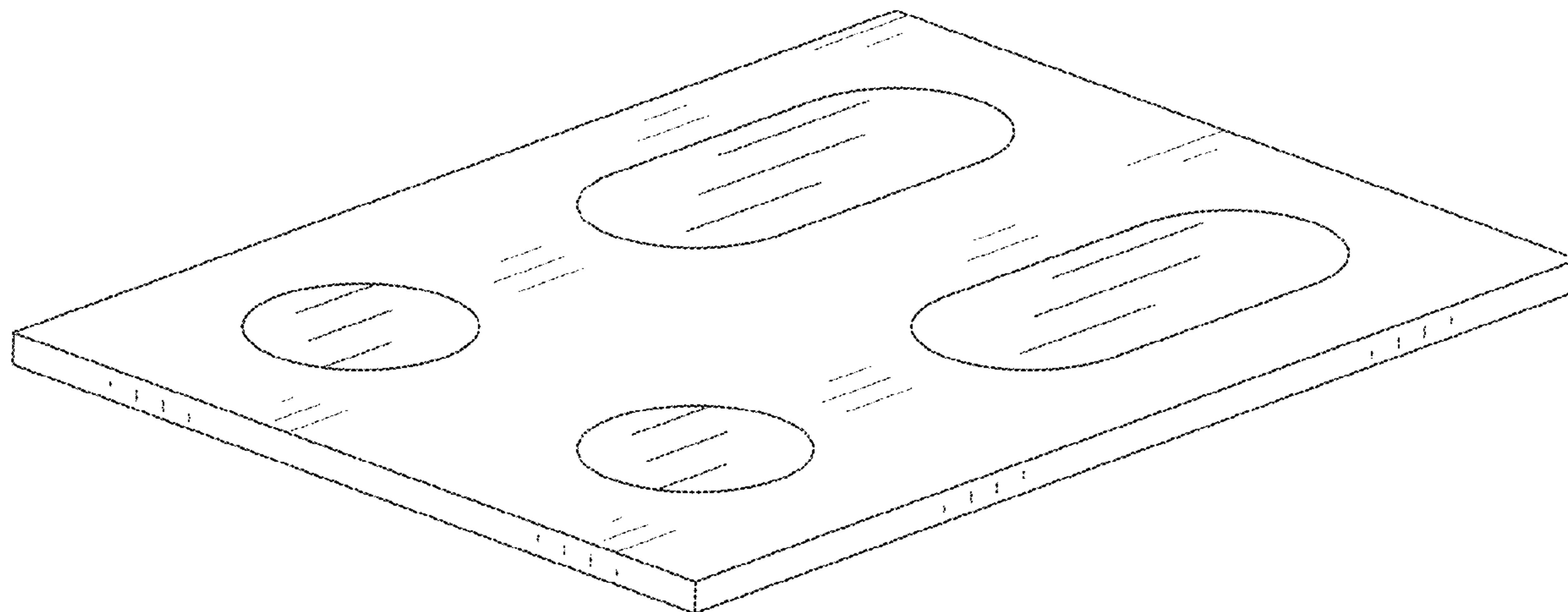
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(57) **CLAIM**  
The ornamental design for a semiconductor device, as shown and described.

**DESCRIPTION**  
FIG. 1 is a perspective view of a semiconductor device showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a right side view thereof;  
FIG. 5 is a left side view thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.

**1 Claim, 7 Drawing Sheets**



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FIG. 1

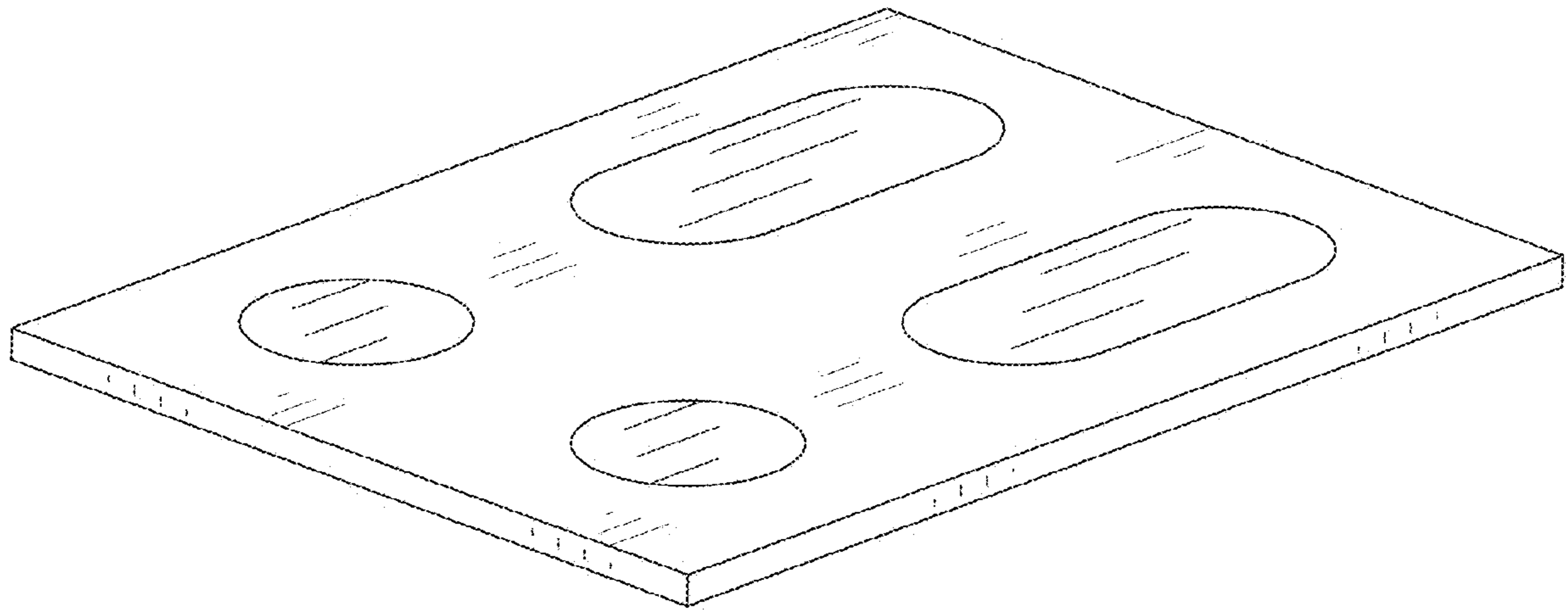


FIG. 2

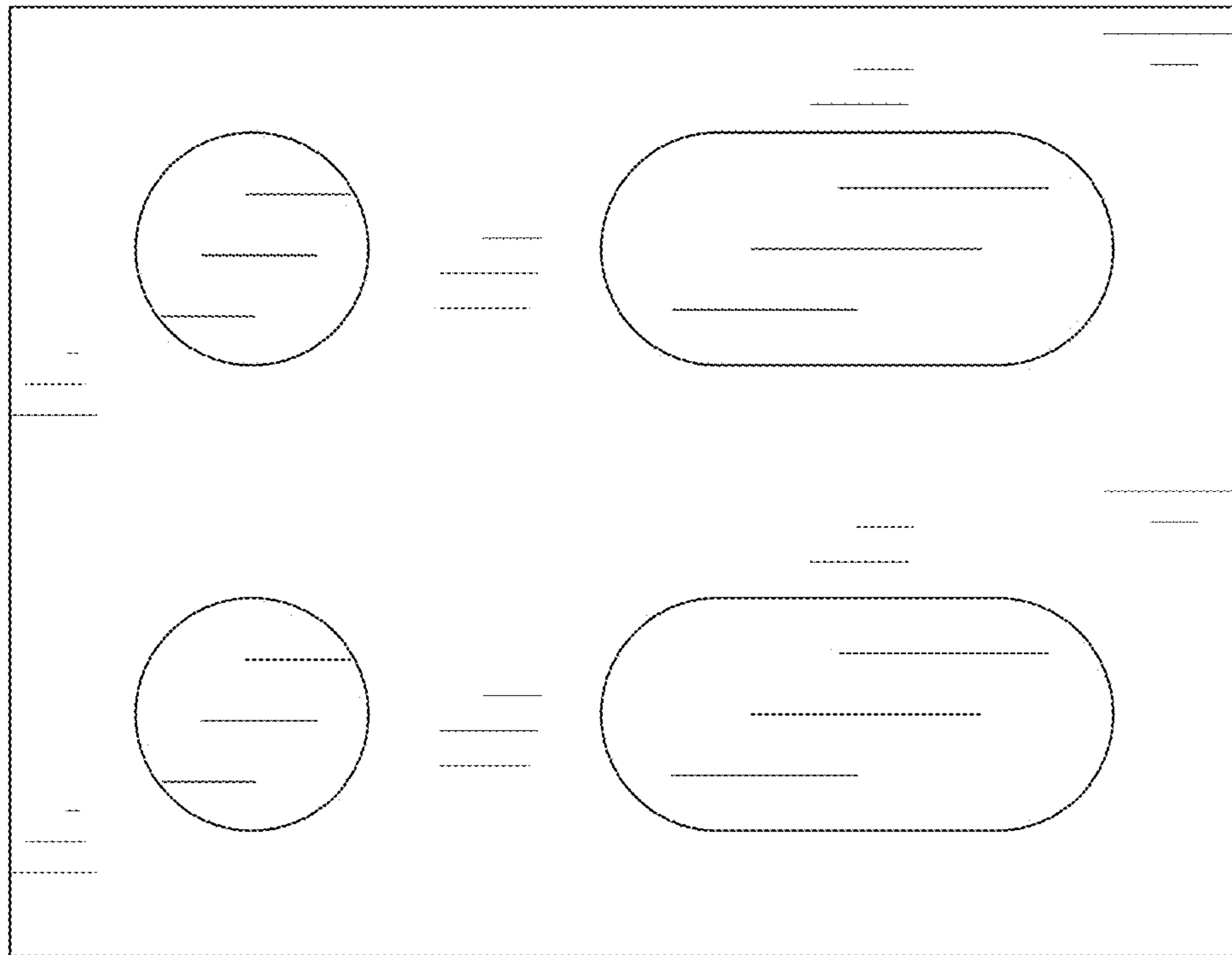


FIG. 3

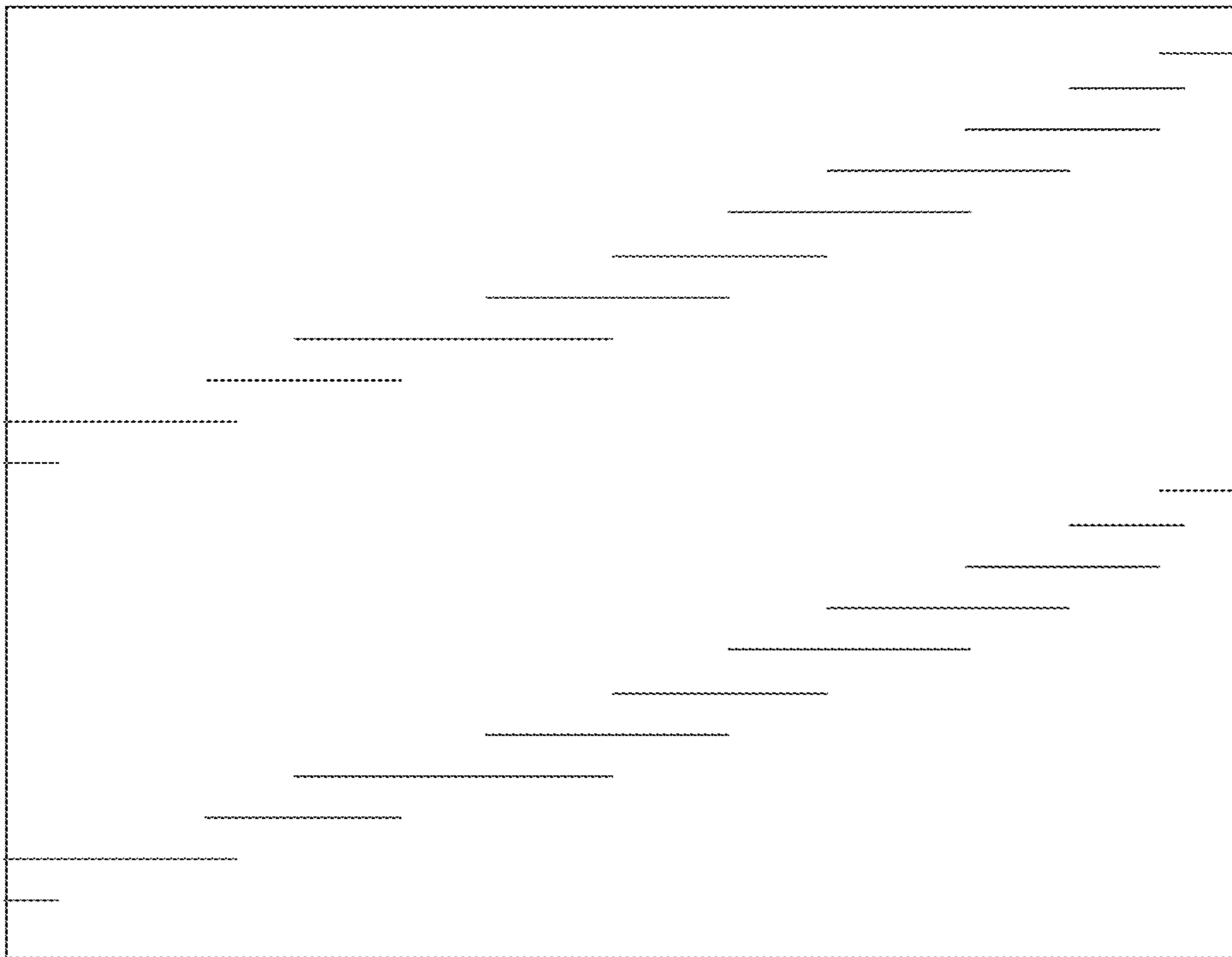


FIG. 4



FIG. 5

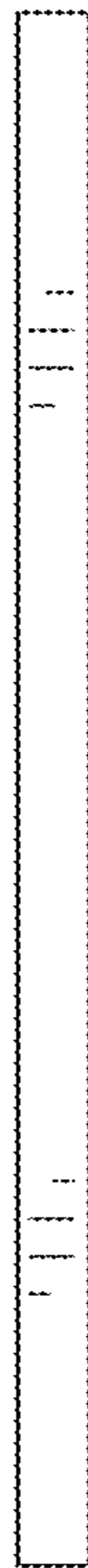


FIG. 6





FIG. 7

